

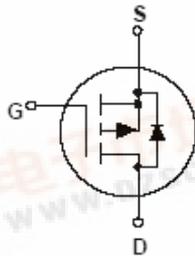
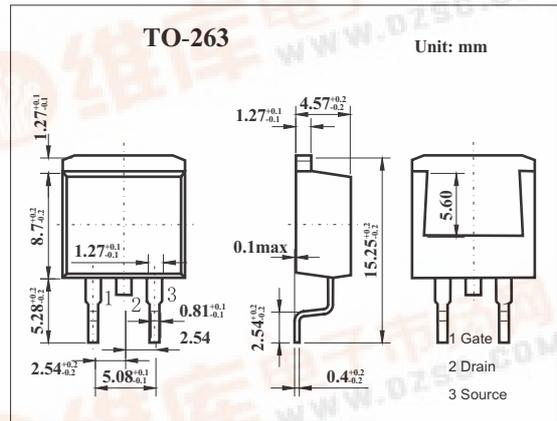
SMD Type MOSFET

## P-Channel 2.5V Specified Enhancement Mode Field Effect Transistor

### KDB4020P(FDB4020P)

■ Features

- -16 A, -20 V.  $R_{DS(on)} = 0.08 \Omega @ V_{GS} = -4.5 V$   
 $R_{DS(on)} = 0.11 \Omega @ V_{GS} = -2.5 V$ .
- Critical DC electrical parameters specified at elevated temperature.
- High density cell design for extremely low  $R_{DS(on)}$ .



■ Absolute Maximum Ratings  $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain to source voltage	$V_{bss}$	-20	V
Gate to source voltage	$V_{gss}$	$\pm 8$	V
Drain current $T_c=25^\circ C$	$I_D$	-16	A
Drain current-pulsed	$I_{dp}$	-48	A
Power dissipation	$P_D$	37.5	W
Derate above $25^\circ C$		0.25	W/ $^\circ C$
Thermal Resistance, Junction-to- Case	$R_{\theta JC}$	4	$^\circ C/W$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	40	$^\circ C/W$
Channel temperature	$T_{ch}$	175	$^\circ C$
Storage temperature	$T_{stg}$	-55 to +175	$^\circ C$

**KDB4020P(FDB4020P)**

## ■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Drain to source breakdown voltage	V <sub>DSS</sub>	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	-20			V
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0, T <sub>C</sub> =25°C			-1	μA
Gate leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±8V, V <sub>GS</sub> =0V			±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.4	-0.58	-1	V
Drain to source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A		0.068	0.08	Ω
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A, T <sub>J</sub> =125°C		0.098	0.13	
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-7A		0.096	0.110	
On-State Drain Current	I <sub>D(on)</sub>	V <sub>GS</sub> = -4.5 V, V <sub>DS</sub> = -5 V	-20			A
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = -5 V, I <sub>D</sub> = -8 A		14		S
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0, f=1MHZ		665		pF
Output capacitance	C <sub>oss</sub>			270		pF
Reverse transfer capacitance	C <sub>rss</sub>			70		pF
Total Gate Charge	Q <sub>g</sub>		V <sub>DS</sub> = -5 V,		9.5	13
Gate-Source Charge	Q <sub>gs</sub>	I <sub>D</sub> = -16 A, V <sub>GS</sub> = -4.5 V *		1.3		nC
Gate-Drain Charge	Q <sub>gd</sub>			2.2		nC
Turn-on delay time	t <sub>on</sub>			8	16	ns
Rise time	t <sub>r</sub>	V <sub>DD</sub> = -5 V, I <sub>D</sub> = -1 A, V <sub>GS</sub> = -4.5 V, R <sub>GEN</sub> = 6 Ω*		24	38	ns
Turn-off delay time	t <sub>off</sub>			50	80	ns
Fall time	t <sub>f</sub>			29	45	ns
Maximum Continuous Drain-Source Diode Forward Current	I <sub>S</sub>				-16	A
Maximum Pulsed Drain-Source Diode Forward Current	I <sub>SM</sub>				-48	A
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -16 A *			-1.2	V

\* Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%